

PRIMERGY BX920 S3

System configurator and order-information guide

January 2014

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PRIMERGY Server

Instructions

This document contains basic product and configuration information that will enable you to configure your system via System-Architect.

Only the tool "System-Arcitect" will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

Please pay attention to the naming conventions:

BX900 S1

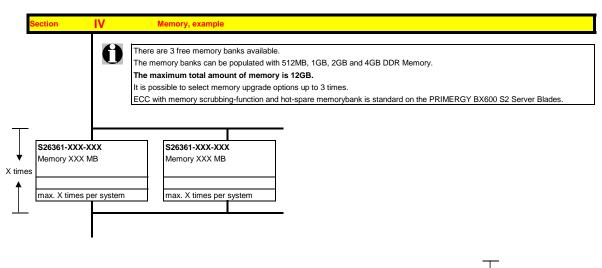
System unit 1nd generation

BX920 S2 Dual Server Blade S2

You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/ System-Architect.

Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.



In one chapter you can only select as many components (here 3x) as the arrow indicates.



Please note that there are information symbols which indicate necessary information.



For further information see:

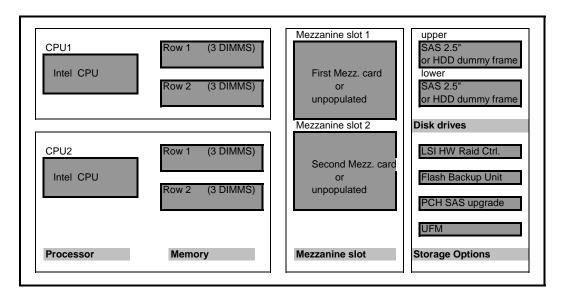
http://ts.fujitsu.com/products/standard_servers/index.html (internet)

https://partners.ts.fujitsu.com/com/order-supply/configurators/primergy_config/Pages/Currentconfigurators.aspx

(extranet)

Prices and availability see price list and PC-/ System-Architect Subject to change and errors excepted

Configuration diagram Dual Server Blade BX920 S3

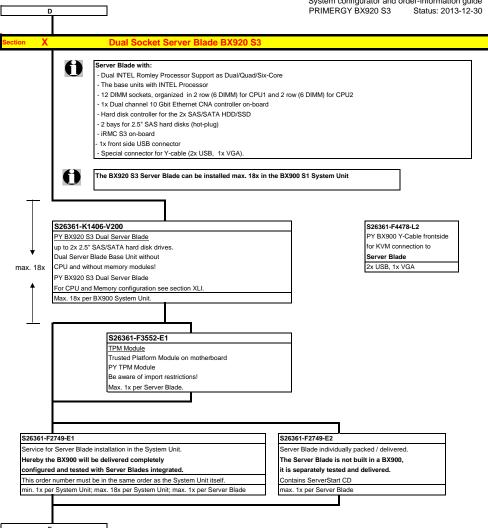


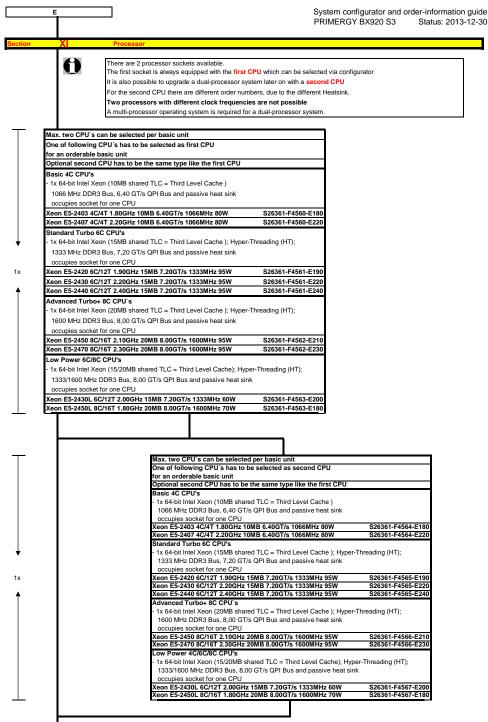
Key:

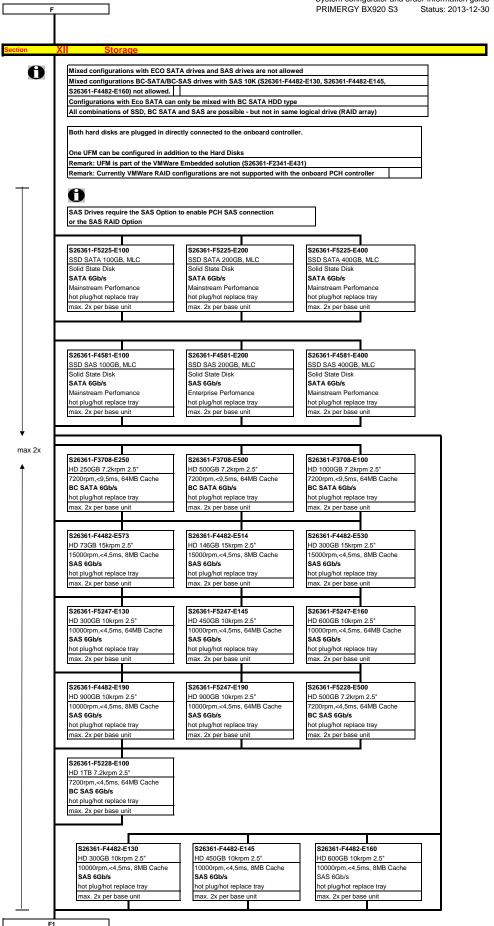
Included in basic unit Option

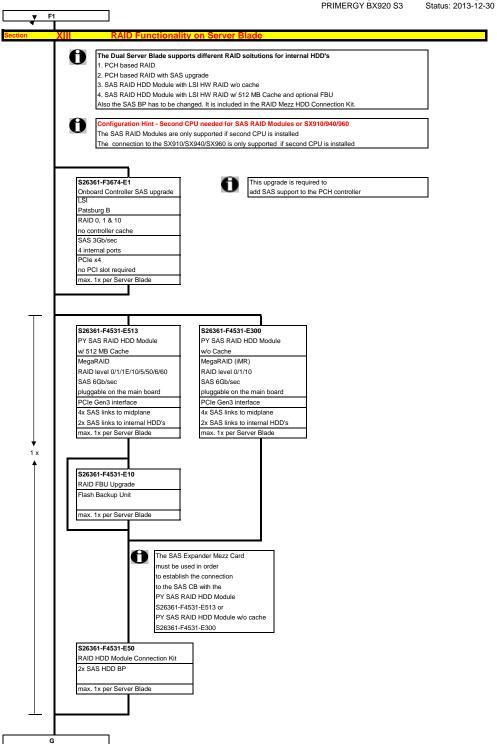
The population order for the CPU is: CPU1 first, then CPU2

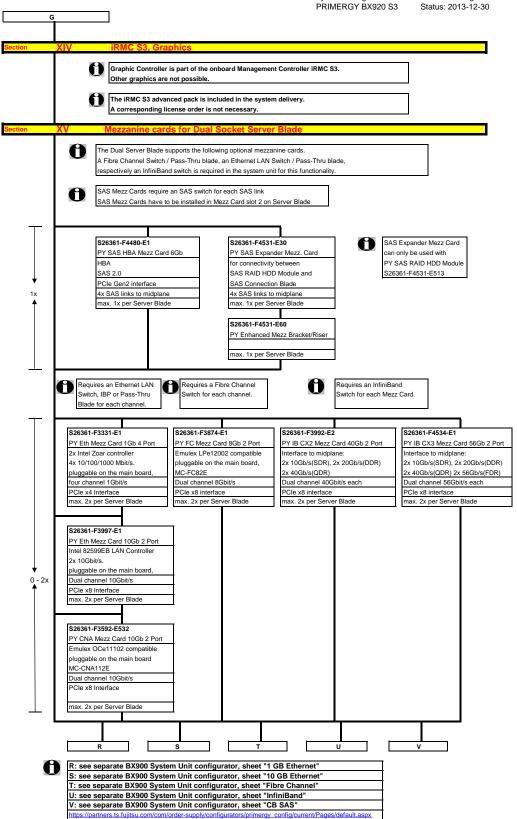
The population order for the DIMMs: for each CPU, the DIMM row 1 (DIMMS 1A 1B 1C) (DIMMS 1D 1E 1F) first, then row 2 (DIMMs 2A, 2B, 2C) (DIMMs 2D, 2E, 2F)











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Section III Memory



- There are 6 memory slots per CPU for max.

192GB LRDIMM (6x 32GB 4R) 96GB RDIMM (6x 16GB 2R) 24GB UDIMM (6x 4GB)

=> max. 384GB for two CPU's (192GB per CPU), using LRDIMM

- The memory area is divided into 3 channels per CPU with 2 slots per channel
- Slot 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3 $\,$

Registered, LR DIMMs and unbuffered memory modules can be selected

No mix of registered, load reduced and unbuffered modules allowed.

Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type.

Memory operating voltage can be set within BIOS (1.5V is default setting for max. speed).

In a 2 DIMMs per channel configuration, following frequencies are supported:

- 1.5V - 1600MHz max (depending on CPU, special memory modules)

- 1.35V - 1333MHz max (depending on CPU)

SDDC (Chipkill) is supported for registered / load reduced x4 organized memory modules only

1.) In the "Independent Channel Mode" is following configuration possible

Channels can be populated in any order in Independent Channel Mode. All four channels may be populated in any order and have no matching requirements. All channels must run at the same interface frequency but individual channels may run at different DIMM timings (RAS latency, CAS latency, and so forth)

No mix of registered, load reduced and unbuffered modules allowed.

2.) "Rank Sparing Mode" configuration

- Within a memory channel, one rank is a spare of the other ranks.

The Spare Rank is held in reserve and is not available as system memory

For the effective memory capacity, please refer to the spreadsheet below.

The BIOS is set to the rank sparing setting.

Minimum configuration is: 2x 1R, 2x 2R or 1x4R DDR3 module per channel

This mode is not supported by x8 organized memory modules

3.) "Performance Mode" configuration

- In this configuration, the memory module population ex factory is spread across all channels.

The BIOS is set to the max. performance for memory.

Minimum configuration is: 3x identical modules

4.) In the "Mirrored Channel Mode" is following configuration possible

- Each memory bank can optionally be equipped with 4x registered or load reduced

In each memory bank channel A and B / C and D of CPU 1 or channel E and F / G and H of CPU 2 have to be

equipped with identical modules for mirrored channel mode. In channel B is always the mirrored memory of channel A of CPU 1

In channel E is always the mirrored memory of channel D of CPU 2

Minimum configuration is: 2x identical modules

This mode is not supported by x8 organized memory modules

G1

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S26361-F3695-E10 Independent Mode

Independent Channel Mode allows all channels to be populated in any order. No specific Memory RAS features are defined

Requires min 1 memory Module per CPU

S26361-F3695-E1 Rank Sparing Mode Installation

BIOS Setup factory preinstalled to this mode. One Rank is spare of other ranks on the same channel. Spare Rank is not shown in System Memory. For effective capacity within a channel, please have a look below.

Supported for RDIMM / LRDIMM only.

1x per CPU Req

Requires min 2x 1R/2R or 1x 4R modules per CPU

S26361-F3695-E2 Performance Mode Installation

BIOS Setup factory preinstalled for max. Performance, LV memory might be set to 1.5V operation. Four identical memory modules

will be equipped in one memory bank to achieve highest memory performance. All four modules are active and full capacity can be used.

Multiple of 3 identical modules to be configured per CPU

S26361-F3695-E3 Mirrored Channel Mode Installation

BIOS Setup factory preinstalled to this mode. Four identical memory modules are always equipped in one memory bank to use the

S26361-F3695-E614

Mirrored channel Mode. Only two modules contain active data, the remain two modules contain mirrored data

Supported for RDIMM / LRDIMM only.

Multiple of 2 identical modules to be configured per CPU



Effective Memory capacity / Rank Sparing Mode, 1 Channel populated											oulated		
	UDIMM						RDIN	LRDIMM					
	2GB	1R	2GB	2R	4GB	1R	8GB	2R	16GB	2R	16GB 4F	32GB 4R	
1DPC	na		na		na		na		na		12GB	24GB	
2DPC	na		na		4GE	4GB		12GB		В	28GB	56GB	



Minimum one memory module or order code per CPU = first memory

Unbuffered Memory (UDIMM) no SDDC (chipkill) support

one DDR3 unbuffered ECC mem. Module, 1.35V
 Choose up to 6 order codes per CPU

Choose up to 6 order codes per CPC

2GB (1x2GB) 1Rx8 L DDR3-1600 U ECC	S26361-F3694-E613
4GB (1x4GB) 2Rx8 L DDR3-1600 U ECC	S26361-F3694-E614

Registered Memory (RDIMM) no SDDC (chipkill) support

one DDR3 registered ECC mem. Module, 1.35V

No mix with any other types of memory modules possible

Choose up to 6x for 2R per CPU

For performance reasons, we do not recommend to configure more than 8 DIMMs per CPU

6x per CPU, max. 2/3 modules per channel

Registered Memory (RDIMM) with SDDC (chipkill) support one DDR3 registered ECC mem. Module, 1.35V

IGB (1x4GB) 2Rx8 L DDR3-1600 R ECC

1333MHz supported with up to 2DPC (6 modules/CPU)

Choose up to 6 order codes per CPU

2 modules per channel Registered Memory (RDIMM) with SDDC (chipkill) support

one DDR3 registered ECC mem. Module, 1.35V

1600MHz supported with up to 2DPC (8 modules/CPU)

at 1.5V

Choose up to 6 order codes per CPU

4GB (1x4GB) 1Rx4 L DDR3-1600 R ECC	S26361-F3697-E614
8GB (1x8GB) 2Rx4 L DDR3-1600 R ECC	S26361-F3697-E615
16GB (1x16GB) 2Rx4 L DDR3-1600 R ECC	S26361-F3697-E616

Load Reduced Memory (LRDIMM) with SDDC (chipkill) support

one DDR3 load reduced ECC mem. Module, 1.35V

Choose up to 6 order codes per CPU

16GB (1x16GB) 4Rx4 L DDR3-1333 LR ECC S26361-F3698-E616 32GB (1x32GB) 4Rx4 L DDR3-1333 LR ECC S26361-F3698-E617 Note 1.)

Max. DDR3 memory speed depends on the memory configuration (No of mem modules per channe) as well as on the CPU type. The memory channel with the lowest speed defines the speed of all CPU channels in the system, also for the channels of the second CPU if configured.

For real memory speed (depending on memory type / population),

please check the spreadsheet "Memory speed" below

new due to supply new due to supply



Mix of memory modules is only possible within the same group

Memory Configuration PRIMERGY BX920 S3

Each CPU offers 6 Slots for DDR3 Memory Modules organised in 2 Banks and 3 Channels.

If you need more than 6 Slots you have to configure the 2nd CPU.

Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not alloved.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration	UDIMM	RDIMM	RDIMM	Application				
	ODIMINI RE		KDIMIM	LRDIMM					
		х8	х8	x4					
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors				
Independant Channel Mode	1, 2 or 3 Modules per Bank	yes	yes	yes	offers max. flexibility, upgradeability, capacity use UDIMM modules for lowest cost				
Mirrored Channel Mode *)	2 identical Modules / Bank	no	no	yes	offers maximum security				
Performance Mode	3 identical Modules / Bank	yes	yes	yes	offers maximum performance and capacity				
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity				

^{*)} For the delivery ex works the system will be prepared with dedicated BIOS setting.

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	1x2GB	1x4GB	1x 16GB	with one CPU
Max. Memory per CPU	4/6 Modules / CPU	6x4GB	6x16GB	6x 32GB	with one CPU
Max. Memory per System	8/12 Modules / System	48GB	96GB	384GB	if second CPU is configured

Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU		Real maximum memory-bus speed depending on CPU type, memory configuration (DPC) and voltage setting (BIOS)																
		UDI	MM 1	600N	ИHz			RD	MM 1	16001	ИHz			LR	DIMM	133	3MHz	
Voltage setting (BIOS)		/ [defa	ault]		1.35\	/	1.5\	1.5V [default]			1.35V			1.5V [default]			1.35V	
	1 DPC	2 DPC	3 DPC	1 DPC	2 DPC	3 DPC	1 DPC	2 DPC	3 DPC	1 DPC	2 DPC	3 DPC	1 DPC	2 DPC	3 DPC	1 DPC	2 DPC	3 DPC
CPU with 1600MHz DDR3 Bus	1333	1333	-	1066	1066	-	1600	1600	-	1333	1333	-	1333	1333	-	1066	1066	-
CPU with 1333MHz DDR3 Bus CPU with 1066MHz DDR3 Bus	1333 1066	1333	- /	1066 1066	1066 1066	-	1333 1066	1333 1066	-	1333 1066	1333 1066	-	1333 1066	1333 1066	-	1066 1066		-

1R - Single Rank

2R - Dual Rank

4R - Quad Rank

1DPC = 1 DIMM per Channel 2DPC = 2 DIMM per Channel 3DPC = 3 DIMM per Channel

Configuration hints:

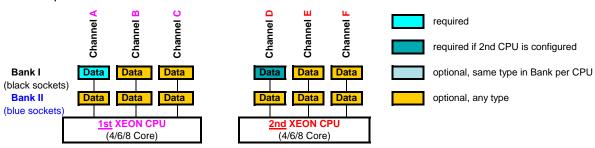
- The memory sockets on the systemboard offer a color coding:

Bank II black sockets
Bank III blue sockets
Bank III green sockets

- A so called Bank consits of 1 memory module on every Channel available on one CPU (examples see below)
 Bank I on CPU 1/2 up to 3 memory modules connected to Channel A - F on the 1st/2nd CPU
 Bank II on CPU 1/2 up to 3 memory modules connected to Channel A - F on the 1st/2nd CPU

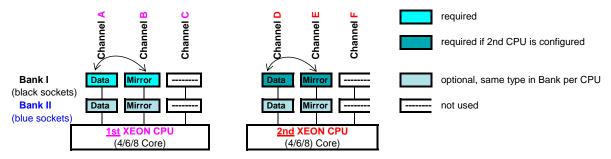
- See below and next page for a detailed descriptions of the memory configuration supported.

1. Independent Channel Mode



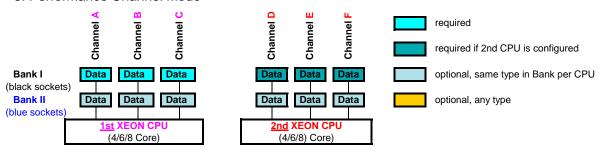
Independent Channel Mode allows all channels to be populated in any order Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

2. Mirrored Channel Mode



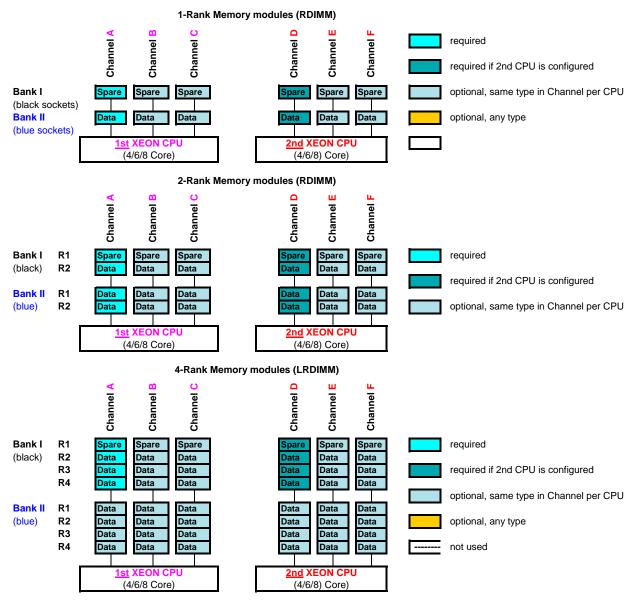
Mirrored Channel Mode requires identical modules on channel A / B (1st CPU) or channel D / E (2nd CPU) 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory If this mode is used, a multiple of 2 identical modules has to be ordered.

3. Performance Channel Mode



Performance Channel Mode requires identical modules on all channels of each Bank per CPU. If this mode is used, a multiple of 3 identical modules has to be ordered.

4. Rank Sparing Mode



Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel. The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max. available memory.

Change Report

Date	Order number	Changes
2013-10-18	optional USB Comps	no longer available
2013-07-18		Added comment about PCH Vmware limitation
2013-01-15	S26361-F3674-E1	Onboard Controller SAS upgrade - Speed corrected from 6GB/s to 3GB/s
2013-01-08	S26361-F5228-E***	New order number for 2.5" BC SAS 7.2K
2013-01-08	S26361-F5247-E130	New order number for SAS 10K (mix with BC-SATA supported, successor for *F5227*)
2012-10-16	hint	SX910/910/960 only with 2nd CPU modified
2012-10-09	hint	SX910/910/960 only with 2nd CPU
2012-10-02		changed USB info
2012-09-04	S26361-F3592-E532	as soon as available removed
2012-07-23	S26361-F5227-E1*	New order for 2.5" 10K SAS HDD supporting mix with 2.5" BC-SATA HDD
2012-06-28		corrected text for 2 end Y-Cable
2012-06-12	S26361-F5225-E*00	New order for SATA SSD's
2012-05-29		Added 1333 RDIMM
2012-05-01		First Release